

TS98-403CC

Serial number 09/285,986

COPY OF PAPERS
ORIGINALLY FILED



AMENDMENT AND RESPONSE TO OFFICE ACTION

TO: COMMISSIONER OF PATENTS AND TRADEMARKS
Washington, D.C. 20231

#18/Amend E
3
Original
JUN -7 2002
RECEIVED
TECHNOLOGY CENTER 2800

From : George O. Saile (Reg. No. 19,572)
20 McIntosh Drive
Poughkeepsie, NY 12603

Date: April 15, 2002

REF: APPLICANT : Chen, Shih-Shiung
SERIAL NO. : 09/285,986
ART UNIT : 2813
FILING DATE : 04/05/99
ATT'Y NO. : TSMC98-403
EXAMINER : Berezny, N
TITLE : A COST EFFECTIVE POLYIMIDE PROCESS TO
SOLVE PASSIVATION EXTRUSION OR DAMAGE AND SOG
DELAMINATES

Sir:


In response to an office action mailed on 02/27/02
please consider the following amendments and remarks with
respect to the above referenced application.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal service as First
Class mail in an envelop addressed to the Commissioner of
Patents and Trademarks, Washington, D.C. 20231, on

May 21, 2002.

Stephen B. Ackerman
(Reg. No 37,761)


Signature

5/21/02
Date